

## Semiconductor Packaging Online Workshop

Thursday 11 February 2021

### Highlights:

- *Die preparation, attach and Interconnection*
- *Package, substrate and encapsulation*
- *Modelling and simulation*
- *Test, inspection and reliability*
- *Packaging Surgery*
- *Online Networking Opportunities*

### Registration:

<http://www.imaps.org.uk>

	<i>Delegates</i>
<i>IMAPS Member</i>	<i>50</i>
<i>Non Member</i>	<i>100</i>
<i>IMAPS Student</i>	<i>30</i>

*Prices - £ exclude VAT*

**“Where the Electronics Packaging Industry Meets Online”**

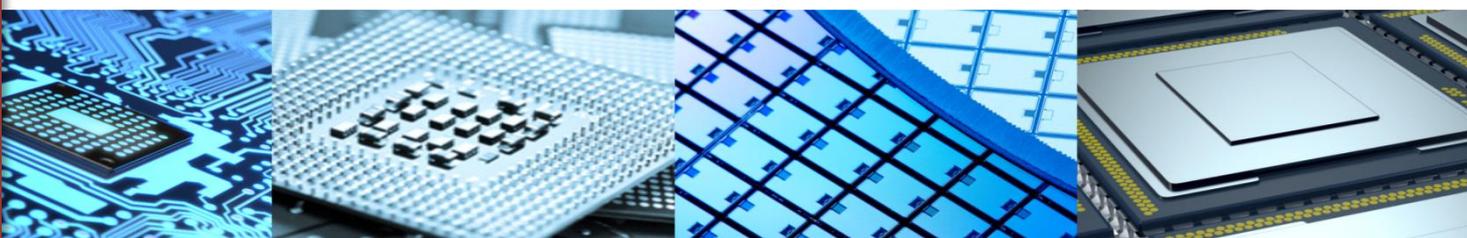
Electronic packaging of semiconductors is often taken for granted with the vast majority of components assembled in the Far East. Electronics packaging and interconnection technologies determine the performance and efficiency of semiconductor devices and can account for up to 80% of the manufacturing costs. Knowledge of the materials and processing technologies involved in the assembly of electronic devices is key to optimising the performance, reliability and cost-effectiveness of electronics systems. This workshop provides a guide to help designers and engineers to navigate through the multitude of electronic packaging materials and processes.

This workshop brings together an array of electronics packaging experts and practitioners to present a comprehensive review of basic packaging technologies including **die preparation, attach and interconnection techniques; package, substrate and encapsulation options, modelling and simulation and test, inspection and reliability.**

The event provides training for staff who need to be aware of the benefits of employing standard packaging technologies for the design and manufacture of electronic products used across multiple sectors including aerospace, automotive, medical, consumer, telecoms and industrial. It will also serve as a refresher for those who wish to expand the breadth of their knowledge and build their network of contacts in the field of electronic packaging.

Join us at the prestigious one day online workshop event to learn, network and source in the field of semiconductor packaging and participate in a packaging surgery.

[Register Here](#)



## Provisional Workshop Agenda:

**09:30 Online Networking**

**10:00 Welcome and Introduction to IMAPS-UK**

**10:10 Session 1: Die Preparation, Attach and Interconnection**

- John Boston – Custom Interconnect Ltd

**11:00 Session 2: Package, Substrate and Encapsulation Options**

- Andy Longford, PandA Europe

**12:00 Lunch**

**13:10 Session 3: Modelling and Simulation**

- Speaker - TBD

**14:10 Session 4: Test, Inspection and Reliability**

- Speaker - TBD

**15:00 Summary**

**15:10 Packaging Surgery**

**16:00 Close**

[Register Here](#)

For further details, please contact IMAPS-UK.

Steve Riches,  
IMAPS-UK Secretariat,  
125 High Street Chesterton,  
Cambridge,  
CB4 1NL  
United Kingdom  
T: 0131 202 9004  
E-mail: [office@imaps.org.uk](mailto:office@imaps.org.uk)



## IMAPS-UK Workshops – Your Chance to Learn:

IMAPS-UK workshops offer delegates the opportunity to learn about the issues and complexities of microelectronics assembly technologies. They provide professional development through in-depth, real-life insights into materials, processes and equipment applied to current and future electronics.

### **Five reasons to attend:**

- It is “Where the Industry Meets Online”
- Access to leaders in the field
- Exposure to a range of Packaging Technologies
- Learn from Case Studies and Industry Trends.
- Discover new industry & business contacts

### **Access to Conference Presentations:**

Attendance at the conference includes post-conference downloadable access to the conference presentations including audio and visuals.

### **Sponsorship Opportunities:**

Please contact us if you or your Company is interested in raising its profile at “**Semiconductor Packaging Workshop**” via our Sponsorship opportunities. In addition to recognition of our sponsors at the start of the Conference, sponsorship provides a free advert in the event handbook, logo on all promotional material and online with weblink.

Please contact the IMAPS Secretariat for further details.

